

Amendments to the Claims:

This listing of claims will replace all prior versions, all listings, of claims in the application:

Listing of Claims:

1. (Original) Process for the production of at least one solderable surface in selected solder regions and of at least one functional surface in function regions differing from the soldering regions on surfaces of copper structures on circuit carriers with the following sequential process stages:
 - (a) a dielectric substrate provided with copper structures is prepared;
 - (b) the solderable surfaces are created by depositing a solderable layer of metal;
 - (c) a covering mask is formed that covers the solder regions and leaves the function regions uncovered;
 - (d) the functional surfaces are created in the function regions; and
 - (e) the covering mask is cleared off.

2. (Original) Process according to claim 1, wherein the at least one solderable surface is made from at least one metal selected from the group comprising tin, silver, bismuth, palladium and their alloys.

3. (Previously Presented) Process according to claim 1, wherein the at least one solderable surface is formed by depositing at least one solderable layer of metal by means of chemical reduction or cementation.

4. (Original) Process according to claim 3, wherein the at least one solderable layer of metal is removed again prior to carrying out stage (d) of the process in the function regions.

5. (Original) Process according to claim 4, wherein the at least one solderable layer of metal is removed by means of an acid etch solution.

6. (Previously Presented) Process according to claim 1, wherein the at least one bondable surface is produced to serve as a functional surface.

7. (Previously Presented) Process according to claim 1, wherein at least one functional surface is made of at least one metal, selected from the group comprising gold, palladium, silver and their alloys.

8. (Original) Process according to claim 7, wherein, for the purpose of producing the at least one functional surface, a basic layer is first applied, said layer being made

from a metal selected from the group comprising nickel, cobalt and their alloys.

9. (Previously Presented) Process according to claim 1, wherein, for the purpose of producing the at least one functional surface, a layer comprising nickel is deposited first and a layer of gold is applied there onto.

10. (Previously Presented) Process according to claim 1, wherein the at least one functional surface is formed by the deposition of at least one functional layer by means of chemical reduction or cementation.

11. (Previously Presented) Process according to claim 1, wherein the covering mask is formed by performing the following steps:

- (c1) application of a layer of photoresist,
- (c2) exposure of the layer of photoresist with a model of the mask in such a manner that the function regions can be led bare in a subsequent development stage and
- (c3) development of the exposed layer of photoresist.

12. (Previously Presented) Process according to claim 1, wherein the covering mask is formed by means of a screen printing process.

13. (Previously Presented) Process according to claim 1, wherein the circuit carriers provided with the copper surfaces are provided with a solder resist mask prior to carrying out step (b) of the procedure, the solder regions and the function regions remaining bare.

Claims 14 and 15 (Cancelled).

16. (Previously Presented) Process according to claim 2, wherein the at least one solderable surface is formed by depositing at least one solderable layer of metal by means of chemical reduction for cementation.

17. (Previously Presented) Process of claim 2, wherein the at least one bondable surface is produced to serve as a functional surface.

18. (Previously Presented) Process according to claim 2, wherein the at least one functional surface is made of at least one metal, selected from the group comprising gold, palladium, silver and their alloys.

19. (Previously Presented) Process according to claim 3, wherein, for the purpose of producing the at least one functional surface, a layer comprising nickel is deposited first and a layer of gold is applied there onto.

20. (Currently Amended) Process according to claim 1, wherein the at least one solderable surface is made from at least one metal selected from the group comprising tin, silver, bismuth, palladium and their alloys; wherein the at least one solderable surface is formed by depositing at least one solderable layer of metal by means of chemical reduction or cementation; wherein the at least one solderable layer of metal is removed again prior to carrying out stage (d) of the process in the function regions; wherein the at least one solderable layer of metal is removed by means of an acid etch solution; wherein the at least one bondable surface is produced to serve as a functional surface; wherein at least one functional surface is made of at least one metal, selected from the group comprising gold, palladium, silver and their alloys; wherein, for the purpose of producing the at least one functional surface, a layer comprising nickel is deposited first and a layer of gold is applied there onto; wherein the at least one functional surface is formed by the deposition of at least one functional layer by means of chemical reduction or cementation; wherein the covering mask is formed by performing the following steps:

(c1) application of a layer of photoresist.

Application Serial No. 09 937,363
Amendment dated August 19, 2003
Reply to final Office Action of May 19, 2003

B-7062

- (c2) exposure of the layer of photoresist with a model of the mask in such a manner that the function regions can be left bare in a subsequent development stage and
- (c3) development of the exposed layer of photoresist.